

REVISIONS		
REV	DESCRIPTION	DATE APPROVED

DETAIL CHART		
ALL UNITS ARE IN INCHES		
FIGURE	SIZE	QTY
+	0.01 PLATED	712
+	0.012 PLATED	537
+	0.013 PLATED	10
+	0.0135 PLATED	1766
+	0.028 PLATED	3
+	0.029 PLATED	17
+	0.03 PLATED	8
+	0.032 PLATED	14
+	0.037 PLATED	16
+	0.042 PLATED	53
+	0.043 PLATED	8
+	0.079 PLATED	6
+	0.125 PLATED	4
+	0.045 NON-PLATED	12
+	0.1 NON-PLATED	2

-.010  
-.012  
-.013  
-.0135

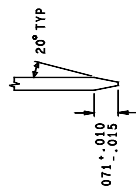
**NOTES:**

1. PRIMARY / COMPONENT SIDE SHOWN.  
2. LAYER ORIENTATION: SEE LAYER DETAIL.  
3. MATERIAL: TETRA- OR MULTI-FUNCTIONAL FR-4 LAMINATES AND PREPREGS PER MIL-P-13649. MINIMUM GLASS TRANSITION TEMPERATURE ( $T_g$ ) OF 170 DEGREE CENTIGRADE REQUIRED. PREPREG CORE DIELECTRICS MUST BE A MINIMUM 2 PLY.

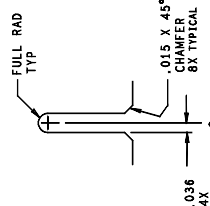
1. THICKNESS:  
a. PLATING:  
- OF 170 DEGREE C. 0.000 (FINISHED)  
- 0.002 (0.001) (FINISHED)  
- 1/2 OZ. PLATED TO 1.5 OZ. ON OUTER LAYERS  
- 1/2 OZ. ON INNER SIGNAL LAYERS.  
- 0 OZ. ON PLANE LAYERS (NO PLATE)  
- MINIMUM AVERAGE COPPER THICKNESS OF 0.0005 AS MEASURED IN WIT-9-55110  
- FINER CONNECTIONS TO BE ELECTROPLATED HARD 150-100 NICKEL (200 MICROINCH) PER IPC-D-273, TABLE 3-9, CLASS 2.

5. FINISH:  
7. ANNULAR RING:  
8. SOLDER MASK:

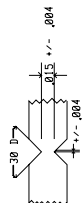
9. BOW AND TWIST:  
0. SILKSCREEN:  
1. PCB:  
2. ELECTRICAL TEST:  
3. HOLE CHART:  
4. SPACING:  
5. SPECIFICATION  
6. FLAME CLASS  
7. MOT  
8. MARKINGS



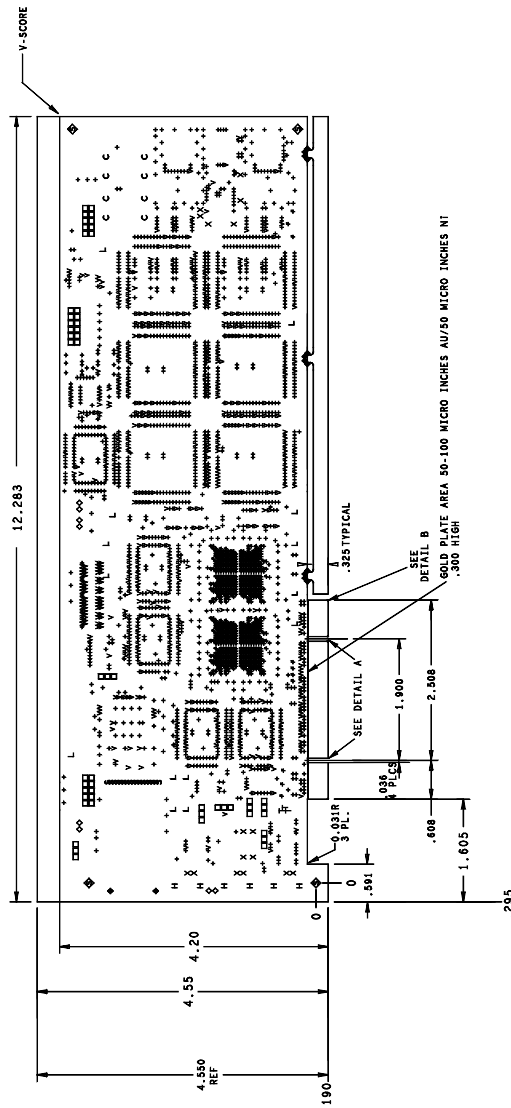
DETAIL C  
SCALE: NONE



DETAIL A  
SCALE: NONE



**SCORE DETAIL**  
**SCALE: NONE**



LAYER DETAIL  
CONSTRUCTION LAMINATE THICKNESS  
AT VENDORS' DISCRETION

[illegible]

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# TITLE FABRICATION DRAWING

RVP8\_RX

SIZE	DRAWING NUMBER	DATE
D	RVP8 - R x	